

# SH7231 Group

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# Setting the SRAM Interface for Bus State Controller

## **Abstract**

This application note describes an example to access an SRAM. The operation is achieved by using the function of the SRAM interface with byte selection equipped in the SH7231 bus state controller.

## **Products**

SH7231

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.



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## 1. Specifications

Get SRAM accessed using the SRAM interface function with byte selection pin on the bus state controller. The SRAM of 2M bytes (1 Mwords x 16 bits) connects to the bus state controller in the bus width of 16 bits.

Table 1.1 lists the peripheral functions used and their applications. Figure 1.1 shows their memory map

**Table 1.1 Peripheral Functions and Applications** 

| Peripheral Function  | Application                                           |
|----------------------|-------------------------------------------------------|
| Bus state controller | Interface for connecting the SRAM with byte selection |

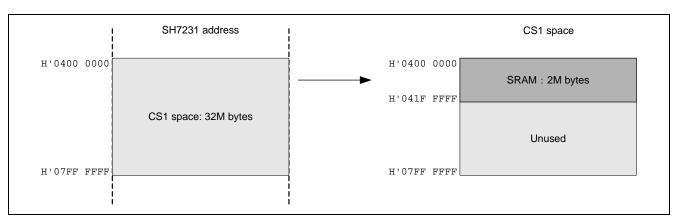


Figure 1.1 SRAM Memory Map

## 2. Operation Confirmation Conditions

The sample code accompanying this application note has been run and confirmed under the conditions below.

**Table 2.1 Operating Conditions** 

| Item                   | Contents                                                                  |  |  |
|------------------------|---------------------------------------------------------------------------|--|--|
| MCU used               | SH7231                                                                    |  |  |
| Devices used           | Renesas Electronics Corporation                                           |  |  |
|                        | SRAM (model: R1LV1616RSA-7S)                                              |  |  |
| Operating frequency    | CPU clock: 100MHz                                                         |  |  |
|                        | Bus clock: 50MHz                                                          |  |  |
|                        | Peripheral clock: 50MHz                                                   |  |  |
| Operating voltage      | • Vcc: 3.3V                                                               |  |  |
|                        | <ul> <li>PVcc: 3.3V or 1.8V</li> </ul>                                    |  |  |
| Integrated development | Renesas Electronics Corporation                                           |  |  |
| environment            | High-performance Embedded Workshop Ver.4.08.00                            |  |  |
| C compiler             | Renesas Electronics Corporation                                           |  |  |
|                        | SuperH RISC engine family C/C++ compiler package V.9.04 Release 00        |  |  |
|                        | Compile options:                                                          |  |  |
|                        | -cpu=sh2afpu -fpu=single -include="\$(WORKSPDIR)\inc"                     |  |  |
|                        | -object="\$(CONFIGDIR)\\$(FILELEAF).obj" -debug -gbr=auto                 |  |  |
|                        | -chgincpath -errorpath -global_volatile=0 -opt_range=all -infinite_loop=0 |  |  |
|                        | -del_vacant_loop=0 -struct_alloc=1 -nologo                                |  |  |
| Operating mode         | MCU expansion mode 2                                                      |  |  |
| Sample code version    | 1.00                                                                      |  |  |
|                        |                                                                           |  |  |

## 3. Reference Application Notes

For additional information associated with this document, refer to the following application notes.

- SH7231 Group Example of Initialization (document No.: R01AN0322EJ)
- SH7231 Group Setting the SDRAM Interface for Bus Controller (Document No.: R01AN0848EJ)



## 4. Hardware

## 4.1 SRAM Specification

Table 4.1 lists the specification of SRAM adopted in this application.

Table 4.1 SRAM Specification in the Application

| Item                  | Description                       |
|-----------------------|-----------------------------------|
| Model                 | R1LV1616RSA-7S                    |
| Volume, Configuration | 16M bits (1 Mwords x 16 bits) x 1 |
| Data bus width        | 16 bits                           |

## 4.2 Pins Used

Table 4.2 lists the pins used and their functions. All the pins are set to I/O ports by default. The change for pin function by the pin function controller is required. This application uses the SRAM interface function with byte selection, therefore the BAS bit in the CS1 space wait control register (CS1WCR) is set to 1.

Table 4.2 Pins Used and their Function

| Pin Name  | 1/0    | Function                                         |
|-----------|--------|--------------------------------------------------|
| A20 to A1 | Output | Address pass                                     |
| D15 to D0 | Input  | Data bus                                         |
| CS1       | Output | Chip select 1                                    |
| RD/WR     | Output | Write enable                                     |
| RD        | Output | Read pulse signal 8read data output enable)      |
| WRH       | Output | Selection for upper byte in data bus (D15 to D8) |
| WRL       | Output | Selection for lower bye in data bus (D7 to D0)   |



# 4.3 A Diagram for Reference

Figure 4.1 shows the sample connection to the SRAM.

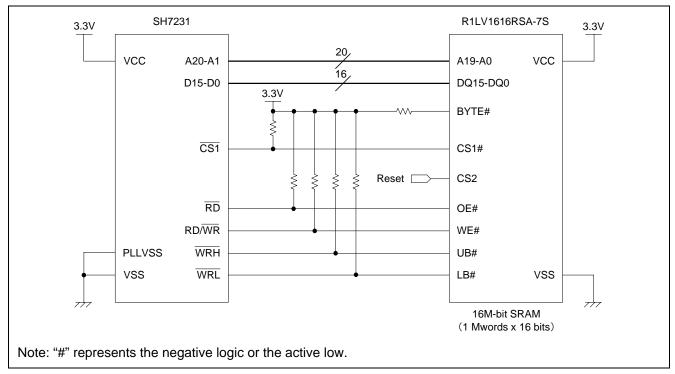


Figure 4.1 Connection to SRAM

## 5. Software

## 5.1 Operation Overview

The sample code sets the bus state controller before executing the main function, and sets the interface with the SRAM with byte selection. The main function carries out no processing but the processing of the endless loop. Therefore this chapter describes only the initial setting for the bus state controller.

#### 5.2 Flowchart

## 5.2.1 Initial Setting for Bus State Controller

Figure 5.1 shows the procedure for initializing the bus state controller.

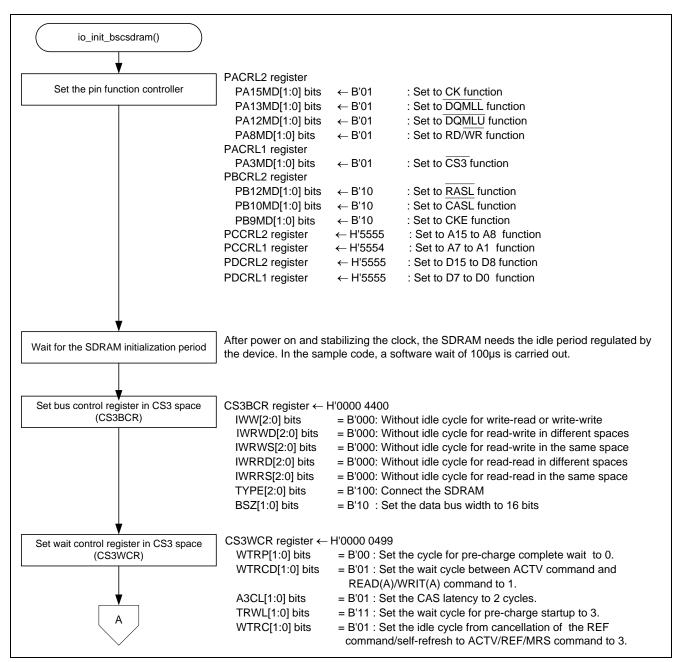


Figure 5.1 Initial Setting for Bus State Controller

## 5.3 Timing Charts

This section describes the access timing of read or write from the SH7231 in the same space to the SRAM with byte selection used in this application.

Figure 5.2 shows the read-write access timing. Figure 5.3 shows the read-write access timing using  $t_{ACC}$  and  $t_{OE}$  to specify the read data set up.

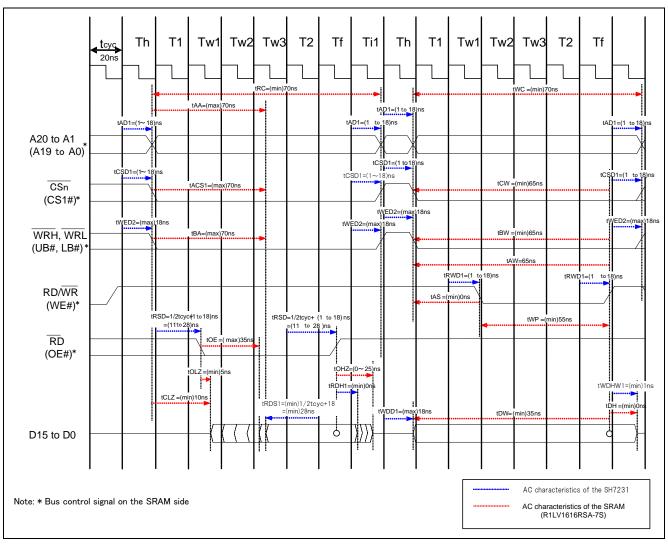


Figure 5.2 Read-write Access Timing

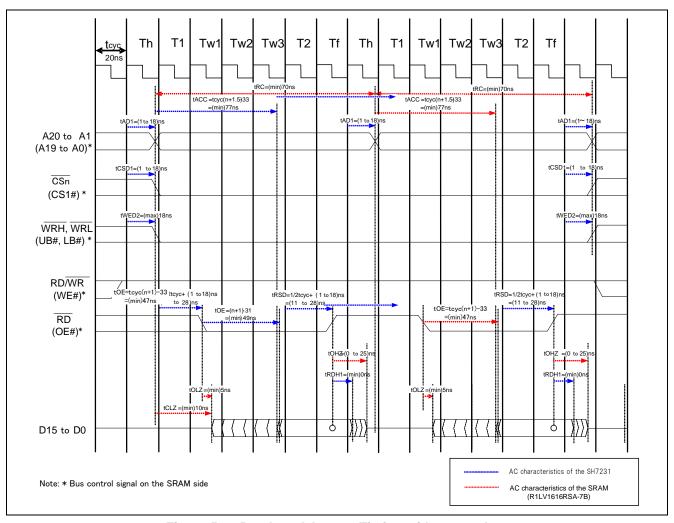


Figure 5.3 Read-read Access Timing with t<sub>ACC</sub> and t<sub>OE</sub>

[Remarks] Specification of set up timing for the data signal when reading

The SH-2/SH-2A series products with the general flash ROM (including this MCU) prescribes two times besides the read data set up time as  $t_{RDS}$  for the data set up timing when reading the general external memory. Refer to the following.

- Read data access time (t<sub>ACC</sub>)
- Access time from read strobe (t<sub>OE</sub>)

Design the read timing to fulfill the following relationship at the same time along with the specification in the  $t_{ACC}$  and  $t_{OE}$ . In this case, the prescription in the  $t_{PDS}$  does not need to be considered.

- The address access time on the SRAM side  $t_{AA}$  \*(max). <=  $t_{ACC}$  (min) on the MCU side.
- The access time from the read strobe on the SRAM side t<sub>OE</sub> \* (max) <= t<sub>OE</sub> (min) on the MCU side.

When designing the read timing to fulfill the prescription in the  $t_{PDS}$ , the above mentioned prescription on the MCU as  $t_{ACC}$  and  $t_{OE}$  do not need to be considered.

Note: "\*" is the symbol which represents the timing prescription on the SRAM (R1LV1616RSA-7S) side used in this application.

## 6. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

#### 7. Reference Documents

Hardware Manual

SH7231 Group User's Manual: Hardware Rev.1.00

The latest version can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest version can be downloaded from the Renesas Electronics website

Development Tool Manual

SuperH C/C++ Compiler Package V.9.04 User's Manual Rev.1.01

The latest version can be downloaded from the Renesas Electronics website.

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| Revision History | SH7231 Group Application Note               |
|------------------|---------------------------------------------|
|                  | Bus State Controller SRAM Interface Setting |

| Rev. | □ Date ——     | Descrip | iption               |  |
|------|---------------|---------|----------------------|--|
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| 1.00 | Dec. 28, 2011 | _       | First edition issued |  |
|      |               |         |                      |  |

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## **General Precautions in the Handling of MPU/MCU Products**

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

#### 1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

— The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flow internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

#### 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
  In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.
- 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

— The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

#### 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.
- 5. Differences between Products

Before changing from one product to another, i.e. to one with a different type number, confirm that the change will not lead to problems.

— The characteristics of MPU/MCU in the same group but having different type numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different type numbers, implement a system-evaluation test for each of the products.

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